TE Internal #: 4-2337939-6

Board-to-Board, 64 Position, 1 mm [.039 in] Centerline, Vertical,

Black, Signal, -40 – 85 °C [-40 – 185 °F], PCI & PCI Express

Connectors

View on TE.com >



Connectors > PCB Connectors > Card Edge Connectors > PCI & PCI Express Connectors



Connector System: Board-to-Board

Number of Positions: 64

PCI Generation: 4

Centerline (Pitch): 1 mm [ .039 in ]

Contact Mating Area Plating Material Thickness: [15 µin]

### **Features**

## **Product Type Features**

Connector & Contact Terminates To	Printed Circuit Board
Connector System	Board-to-Board
Sealable	No

## **Configuration Features**

Number of PCB Mount Retention Features	2
Number of Positions	64
PCB Mount Orientation	Vertical
Ejector	Without

## **Body Features**

Primary Product Color	Black
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#### **Contact Features**

Contact Current Rating (Max)	1.1 A
Contact Underplating Material	Nickel
Contact Mating Area Plating Material	Gold (Au)
Contact Base Material	Copper Alloy
	15 μin

#### **Termination Features**



Mechanical Attachment	
Connector Mounting Type	Board Mount
PCB Mount Retention Type	SMT Hold-Down
Housing Features	
Centerline (Pitch)	1 mm[.039 in]
Dimensions	
PCB Thickness (Accepted)	1.57 mm
Usage Conditions	
Operating Temperature Range	-40 - 85 °C[-40 - 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
Bus Type	PCI Express
PCI Generation	4
Packaging Features	

## **Product Compliance**

Packaging Method

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

Box & Tray

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as



EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

## **Compatible Parts**



# Customers Also Bought





MYLAR,HT



















## **Documents**

**CAD Files** 

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_4-2337939-6\_A.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_4-2337939-6\_A.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_4-2337939-6\_A.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use

## **Product Specifications**

AMP El Series, Connector

Japanese

**Product Specification** 

Japanese

**Product Specification** 

English

## Agency Approvals

**UL Report** 

English

**UL Report** 

English